

PMP8944_REVA_BOM BOM

COUNT	RefDes	Value	Description	Size	Part Number	MFR
2	C1, C78	0.01uF	Capacitor, Ceramic, 100V, X7R, 10%	0603	STD	STD
1	C12	470uF	CAP ALUM 470UF 35V 20% SMD	0.543 x 0.543	EEV-FK1V471Q	Panasonic
1	C13	0.1uF	Capacitor, Ceramic, 100V, X7R, 15%	1206	STD	STD
3	C14, C16, C20	0.1uF	Capacitor, Ceramic Chip, 16V, X7R, 10%	0402	Std	Std
1	C17	47uF	Capacitor, Aluminum, 16V, 20%	0.201 x 0.262 inch	EEVFK1C470UR	Panasonic
1	C18	330pF	Capacitor, Ceramic, 3kV, NP0, C0G, 10%	1808	Std	Std
1	C19	1uF	Capacitor, Ceramic, 16V, X7R, 10%	0603	STD	STD
2	C2, C15	10pF	Capacitor, Ceramic Chip, 25V, X7R, 10%	0402	Std	Std
1	C21	0.047uF	Capacitor, Ceramic Chip, 25V, X7R, 10%	0402	Std	Std
1	C22	100pF	Capacitor, Ceramic Chip, 25V, X7R, 10%	0402	Std	Std
1	C23	2200pF	Capacitor, Ceramic Chip, 25V, X7R, 10%	0402	Std	Std
1	C24	1000pF	Capacitor, Ceramic Chip, 25V, X7R, 10%	0402	Std	Std
1	C25	4.7uF	Capacitor, Ceramic, 25V, X7R, 15%	1206	STD	STD
8	C3, C4, C5, C6, C7, C8, C10, C11	4.7uF	Capacitor, Ceramic, 50V, X7R, 15%	1210	STD	STD
1	C9	100uF	CAP ALUM 100UF 35V 20% SMD	0.328 x 0.390 inch	EEV-FK1V101XP	Panasonic
1	D1	MURA120T3	Diode, UltraFast Rectifier, 1-A, 200-V	403A	MURA120T3	On Semi
6	D2, D5, D6, D7, D10, D11	MMSD914T1	Diode, Switching, 100-V, 200-mA, 225-mW,	SOD-123	MMSD914T1	On Semi
2	D3, D8	BAS21	Diode, Switching, 200-mA, 200-V, 330-mW	SOT23	BAS21	Zetex
2	D4, D9	10V	Diode, Zener, 10-V	SOT23	STD	STD
2	J1, J2	ED120/2DS	Terminal Block, 2-pin, 15-A, 5.1mm	0.40 x 0.35 inch	ED120/2DS	OST
1	J7	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	0.100 inch x 2	PEC02SAAN	Sullins
1	L1	4.7uH	Inductor, SMT, 18-A, 1.8-milliohm	0.790 x 0.770 inch	SER2013-472MX	Coilcraft
1	L2	15uH		1.100 x 1.100 inch	SER2918H-153KL	Coilcraft
1	L3	1mH	INDUCT PWR 1MH SMD	0.244 x 0.244 inch	PG0087.105NLT	Pulse
2	Q1, Q8	BF622,115	TRANS NPN 250V 50MA SOT89	0.126 X 0.250 inch	BF622,115	NXP
1	Q10	MMBT2222A	TRANSISTOR, NPN, HIGH-PERFORMANCE, 500mA	SOT-23	MMBT2222A	Fairchild
3	Q2, Q9, Q11	MMBT2907A	Transistor, PNP, -60V, -600mA, 225-W	SOT23	MMBT2907ALT1	On Semi
1	Q3	FDC3535	MOSFET P-CH 80V 6-SSOT	SuperSOT-6	FDC3535	Fairchild
2	Q4, Q5	BSC109N10NS3	MOSFET N-CH 100V 63A 8TDSO	TDSON-8	BSC109N10NS3	Infineon
2	Q6, Q7	BSC190N15NS3	MOSFET N-CH 150V 50A TDSON-8	TDSON-8	BSC190N15NS3	Infineon
1	R1	1	Resistor, Chip, 1/16W, 5%	0805	Std	Std
1	R10	976k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R11	1.21k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R12	36.5k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
2	R13, R15	121k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R14	80.6k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
2	R17, R19	0	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R18	2k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R2	1k	Resistor, Chip, 1/16W, 5%	0805	Std	Std
1	R22	49.9k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R24	150k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R25	5.76k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
2	R3, R63	20k	Resistor, Metal Oxide, 1W, 5%	2512	STD	STD
2	R4, R7	10k	Resistor, 1/4W, 5%	1210	Std	Std
1	R5	1	Resistor, Chip, 1/2W, 5%	2010	Std	Std
2	R6, R21	10k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
2	R8, R20	60.4k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
3	R9, R16, R23	1k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	T1	PA1005.100NL	Transformer, Current Sense	0.284 x 0.330 inch	PA1005.100NL	Pulse
1	T3	40 uH	Transformer, ±25%	26.4x32 mm	PA3847NL	Pulse
3	TP1, TP3, TP5	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
2	TP2, TP4	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	U1	UCC2897APW	IC, Current-Mode Active Clamp PWM Controller	PW20	UCC2897APW	TI
1	U2	TCMT1107	IC, Photocoupler	MF4	TCMT1107	Vishay
1	U3	TL431AIDBZ	IC, Precision Adjustable Shunt Regulator	SOT23-3	TL431AIDBZ	TI

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